LIQUID RESIN COMPOSITION, SEMICONDUCTOR ELEMENT HAVING ADHESIVE LAYER, METHOD OF PRODUCING THE SAME, AND SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

A liquid resin composition includes (A) an epoxy resin component, (B) a compound having a phenolic hydroxyl group, (C) an imidazole compound, and (D) a diazabicyclo compound, the epoxy resin component (A) being liquid at room temperature.

No suitable figure